



Material Content Data Sheet



Sales Product Name		BSP149 H6327		Issued		23. January 2018		
MA#		MA001073668						
Package		PG-SOT223-4-21		Weight*		113.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.078	0.07		684	
	non noble metal	tin	7440-31-5	0.020	0.02		176	
	inorganic material	silicon	7440-21-3	0.881	0.77	0.86	7749	8609
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		446	
	non noble metal	chromium	7440-47-3	0.152	0.13		1339	
	non noble metal	copper	7440-50-8	50.489	44.44	44.62	444318	446192
wire	non noble metal	copper	7440-50-8	0.015	0.01	0.01	135	135
encapsulation	organic material	carbon black	1333-86-4	0.600	0.53		5277	
	plastics	epoxy resin	-	8.994	7.92		79150	
	inorganic material	silicondioxide	60676-86-0	50.366	44.32	52.77	443238	527665
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12884	12884
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4515	4515
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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